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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	20 ns
Voltage Supply - Internal	4.5V ~ 5.5V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	160
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m5-256-160-20yi-1

Table 1. MACH 5 Device Features ¹

Feature	M5-128/1 M5LV-128		M5-192/1	M5-256/1 M5LV-256		M5-320 M5LV-320		M5-384 M5LV-384		M5-512 M5LV-512	
Supply Voltage (V)	5	3.3	5	5	3.3	5	3.3	5	3.3	5	3.3
Macrocells	128	128	192	256	256	320	320	384	384	512	512
Maximum User I/O Pins	120	120	120	160	160	192	160	160	160	256	256
t _{PD} (ns)	5.5	5.5	5.5	5.5	5.5	6.5	6.5	6.5	6.5	6.5	6.5
t _{SS} (ns)	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0
t _{COS} (ns)	4.5	4.5	4.5	4.5	4.5	5.0	5.0	5.0	5.0	5.0	5.0
f _{CNT} (MHz)	182	182	182	182	182	167	167	167	167	167	167
Typical Static Power (mA)	35	35	45	55	55	70	70	75	75	100	100
IEEE 1149.1 Boundary Scan Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PCI-Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

Note:

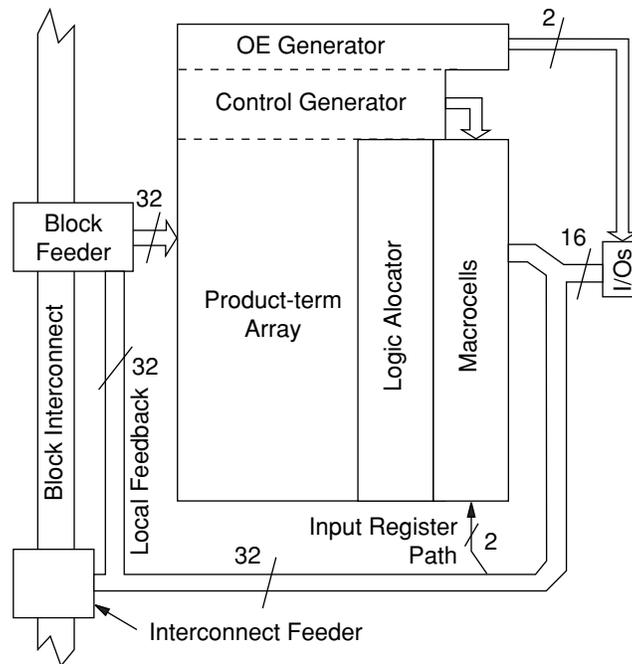
1. "M5-xxx" is for 5-V devices. "M5LV-xxx" is for 3.3-V devices.

GENERAL DESCRIPTION

The MACH[®] 5 family consists of a broad range of high-density and high-I/O Complex Programmable Logic Devices (CPLDs). The fifth-generation MACH architecture yields fast speeds at high CPLD densities, low power, and supports additional features such as in-system programmability, Boundary Scan testability, and advanced clocking options (Table 1). The MACH 5 family offers 5-V (M5-xxx) and 3.3-V (M5LV-xxx) operation.

Manufactured in state-of-the-art ISO 9000 qualified fabrication facilities on E²CMOS process technologies, MACH 5 devices are available with pin-to-pin delays as fast as 5.5 ns (Table 2). The 5.5, 6.5, 7.5, 10, and 12-ns devices are compliant with the *PCI Local Bus Specification*.

Select devices have been discontinued. See Ordering Information section for product status.



20446G-002

Figure 2. PAL Block Structure

Product-Term Array and Logic Allocator

The product-term array uses the same sum-of-products architecture as PAL devices and consists of 32 inputs (plus their complements) and 64 product terms arranged in 16 **clusters**. A cluster is a sum-of-products function with either 3 or 4 product terms.

Logic allocators assign the clusters to macrocells. Each macrocell can accept up to eight clusters of three or four product terms, but a given cluster can only be steered to one macrocell (Table 4). If only three product terms in a cluster are steered, the fourth can be used as an input to an XOR gate for separate logic generation and/or polarity control.

The **wide logic allocator** is comprised of all 16 of the individual logic allocators and acts as an output switch matrix by reassigning logic to macrocells to retain pinout as designs change. The logic allocation scheme in the MACH 5 device allows for the implementation of large equations (up to 32 product terms) with only one pass through the logic array.

Table 4. Product Term Steering Options for PT Clusters and Macrocells

Macrocell	Available Clusters	Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂ , C ₃ , C ₄	M ₈	C ₅ , C ₆ , C ₇ , C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₁	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅	M ₉	C ₆ , C ₇ , C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₂	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆	M ₁₀	C ₇ , C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₃	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇	M ₁₁	C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₄	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇	M ₁₂	C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₅	C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇ , C ₈	M ₁₃	C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇ , C ₈ , C ₉	M ₁₄	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₃ , C ₄ , C ₅ , C ₆ , C ₇ , C ₈ , C ₉ , C ₁₀	M ₁₅	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅

Select devices have been discontinued. See Ordering Information section for product status.

Macrocells

The macrocells for MACH 5 devices consist of a storage element which can be configured for combinatorial, registered or latched operation (Figure 3). The D-type flip-flops can be configured as T-type, J-K, or S-R operation through the use of the XOR gate associated with each macrocell.

Each PAL block has the capability to provide two input registers by using macrocells 0 and 15. In order to use this option, these macrocells must be accessed via the I/O pins associated with macrocells 3 and 12, respectively. Once the macrocell is used as an input register, it cannot be used for logic, so its clusters can be re-directed through the logic allocator to another macrocell. The

I/O pins associated with macrocells 0 and 15 can still be used as input pins. Although the I/O pins for macrocells 3 and 12 are used to connect to the input registers, these macrocells can still be used as “buried” macrocells to drive device logic via the matrix.

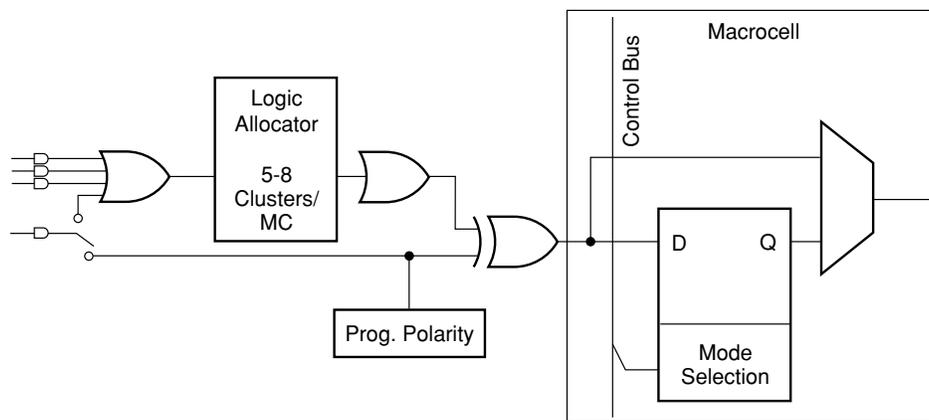


Figure 3. Macrocell Diagram

20446G-003

Control Generator

The control generator provides four configurable clock lines and three configurable set/reset lines to each macrocell in a PAL block. Any of the four clock lines and any of the three set/reset lines can be independently selected by any flip-flop within a block. The clock lines can be configured to provide synchronous global (pin) clocks and asynchronous product term clocks, sum term clocks, and latch enables (Figure 4). Three of the four global clocks, as well as two product-term clocks and one sum-term clock, are available per PAL block. Positive or negative edge clocking is available as well as advanced clocking features such as **complementary** and **biphase** clocking. Complementary clocking provides two clock lines exactly 180 degrees out of phase, and is useful in applications such as fast data paths. A biphase clock line clocks flip-flops on both the positive and negative edges of the clock. The configuration options for the four clock lines per PAL block are as follows:

Clock Line 0 Options

- ◆ Global clock (0, 1, 2, or 3) with positive or negative edge clock enable
- ◆ Product-term clock ($A*B*C$)
- ◆ Sum-term clock ($A+B+C$)

Clock Line 1 Options

- ◆ Global clock (0, 1, 2, or 3) with positive edge clock enable
- ◆ Global clock (0, 1, 2, or 3) with negative edge clock enable

Select devices have been discontinued.
See Ordering Information section for product status.

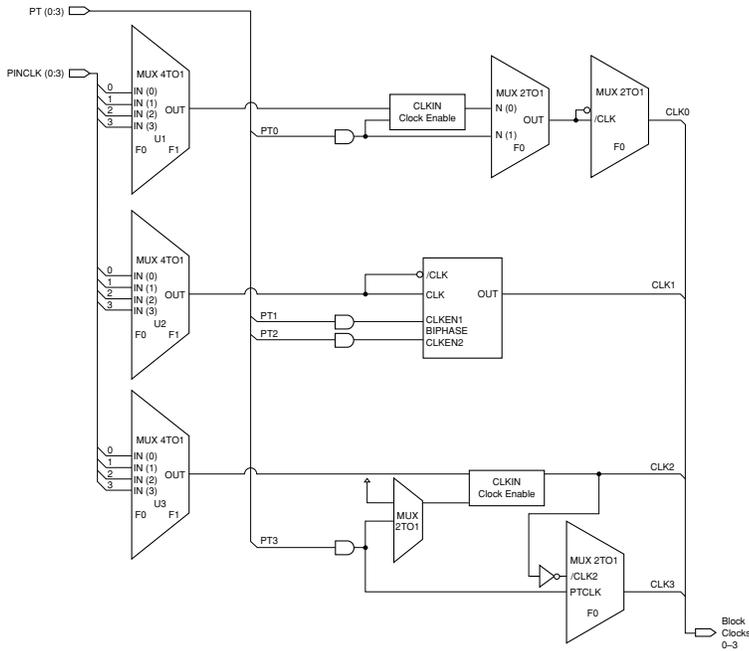
- ◆ Global clock (0, 1, 2, or 3) with positive and negative edge clock enable (biphase)

Clock Line 2 Options

- ◆ Global clock (0, 1, 2, or 3) with clock enable

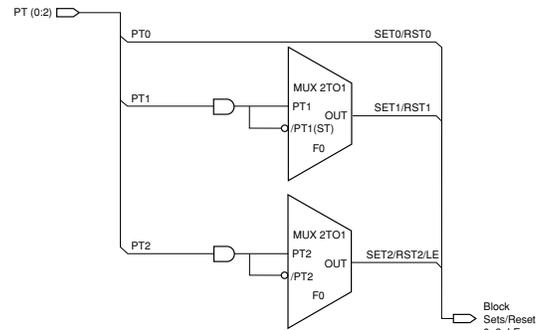
Clock Line 3 Options

- ◆ Complement of clock line 2 (same clock enable)
- ◆ Product-term clock (if clock line 2 does not use clock enable)



20446G-004

Figure 4. Clock Generator



20446G-005

Figure 5. Set/Reset Generator

The set/reset generation portion of the control generator (Figure 5) creates three set/reset lines for the PAL block. Each macrocell can choose one of these three lines or choose no set/reset at all. All three lines can be configured for product term set/reset and two of the three lines can be configured as sum term set/reset and one of the lines can be configured as product-term or sum-term latch enable. While the set/reset signals are generated in the control generator, whether that signal sets or resets a flip-flop is determined within the individual macrocell. The same signal can set one flip-flop and reset another. PT2 or /PT2 can also be used as a latch enable for macrocells configured as latches.

Select devices have been discontinued. See Ordering Information section for product status.

SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS ¹

Both the 3.3-V and 5-V V_{CC} MACH 5 devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V devices will accept inputs up to 5.5 V. Both the 3.3-V and 5-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

Note:

1. Excludes original M5-128, M5-192, and M5-256 while M5-128/1, M3-192/1 and M5-256/1 are supported. Please refer to Application Note titled “Hot Socketing and Mixed Supply Design with MACH 4 and MACH 5 Devices”.

BUS-FRIENDLY INPUTS AND I/Os

All MACH 5 devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is a good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level “1.” For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

There are 4 power/speed options in each MACH 5 PAL block (Table 5). The speed and power tradeoff can be tailored for each design. The signal speed paths in the lower-power PAL blocks will be slower than those in the higher-power PAL blocks. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in a lower-power mode. In large designs, there may be several different speed requirements for different portions of the design.

Table 5. Power Levels

High Speed/High Power	100% Power
Medium High Speed/Medium High Power	67% Power
Medium Low Speed/Medium Low Power	40% Power
Low Speed/Low Power	20% Power

PROGRAMMABLE SLEW RATE

Each MACH 5 device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic and the clock must be inactive until the reset delay time has elapsed.

Select devices have been discontinued. See Ordering Information section for product status.

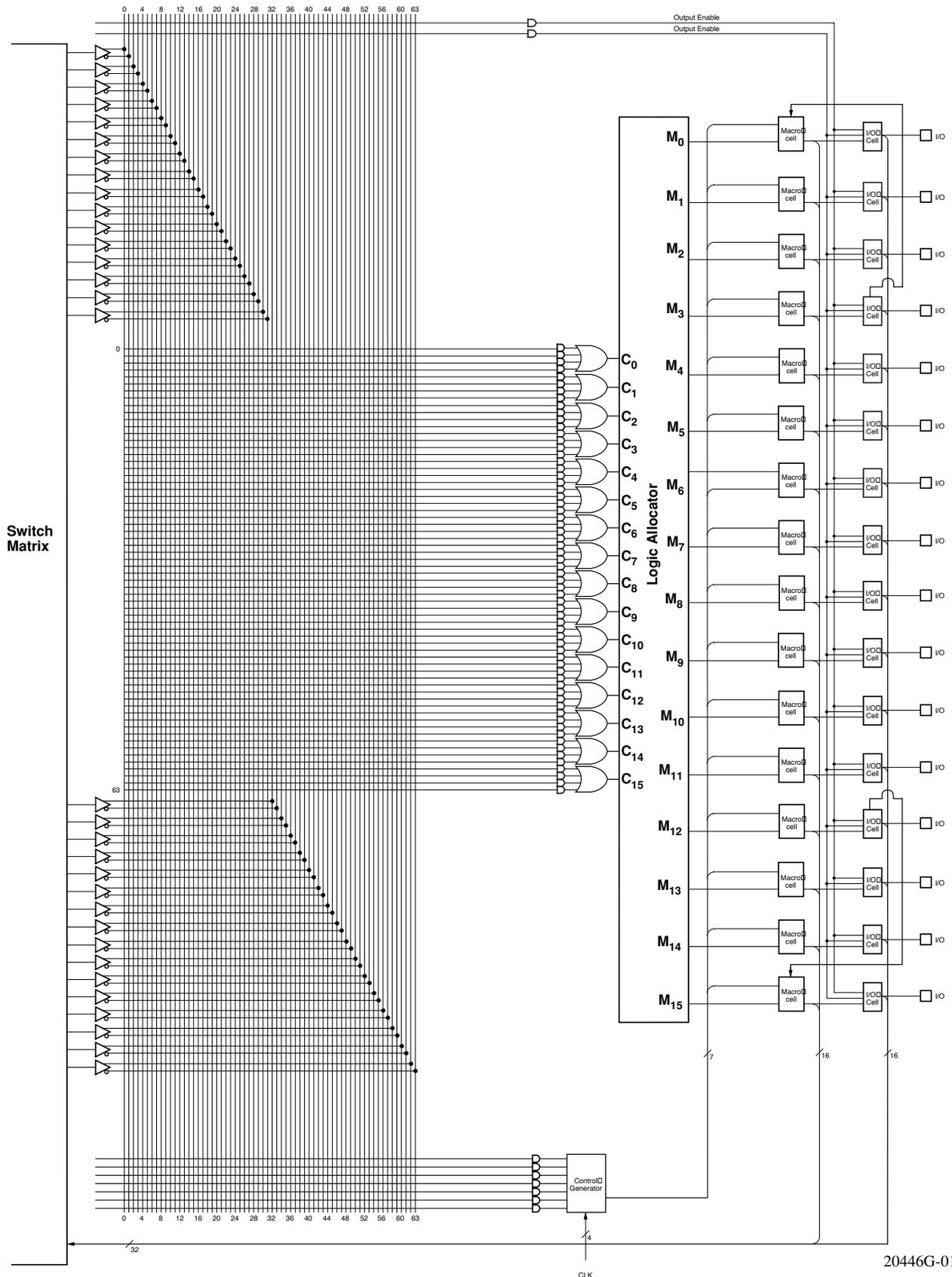


SECURITY BIT

A programmable security bit is provided on the MACH 5 devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

**Select devices have been discontinued.
See Ordering Information section for product status.**

MACH 5 PAL BLOCK

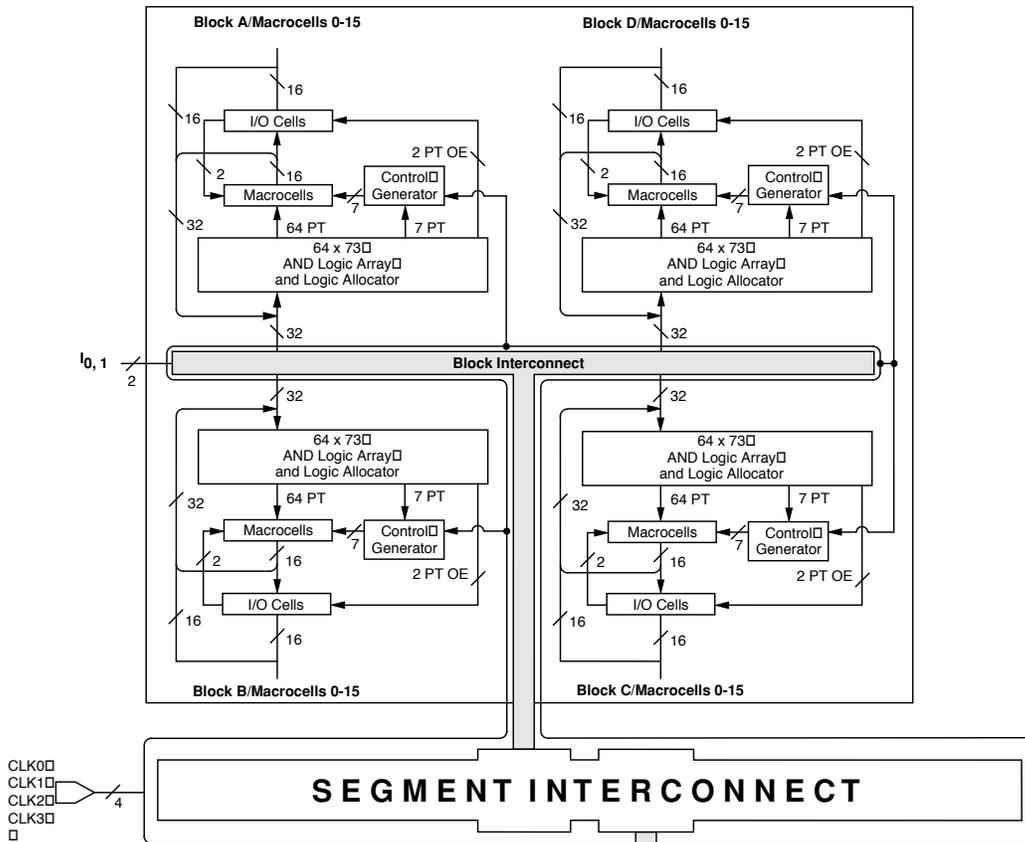


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See Ordering Information section for product status.

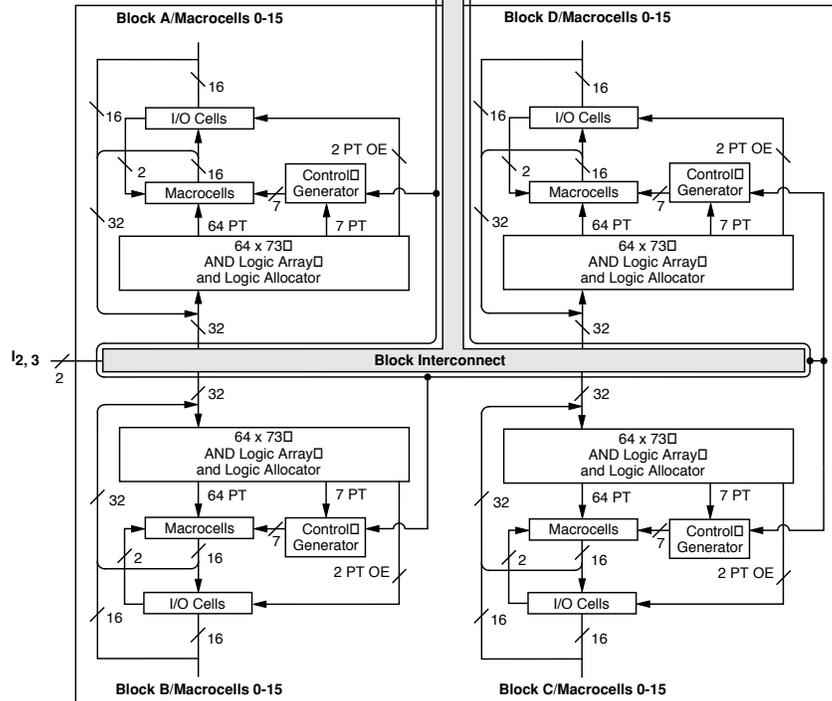
20446G-015

BLOCK DIAGRAM — M5(LV)-128/XXX

SEGMENT 0



SEGMENT INTERCONNECT

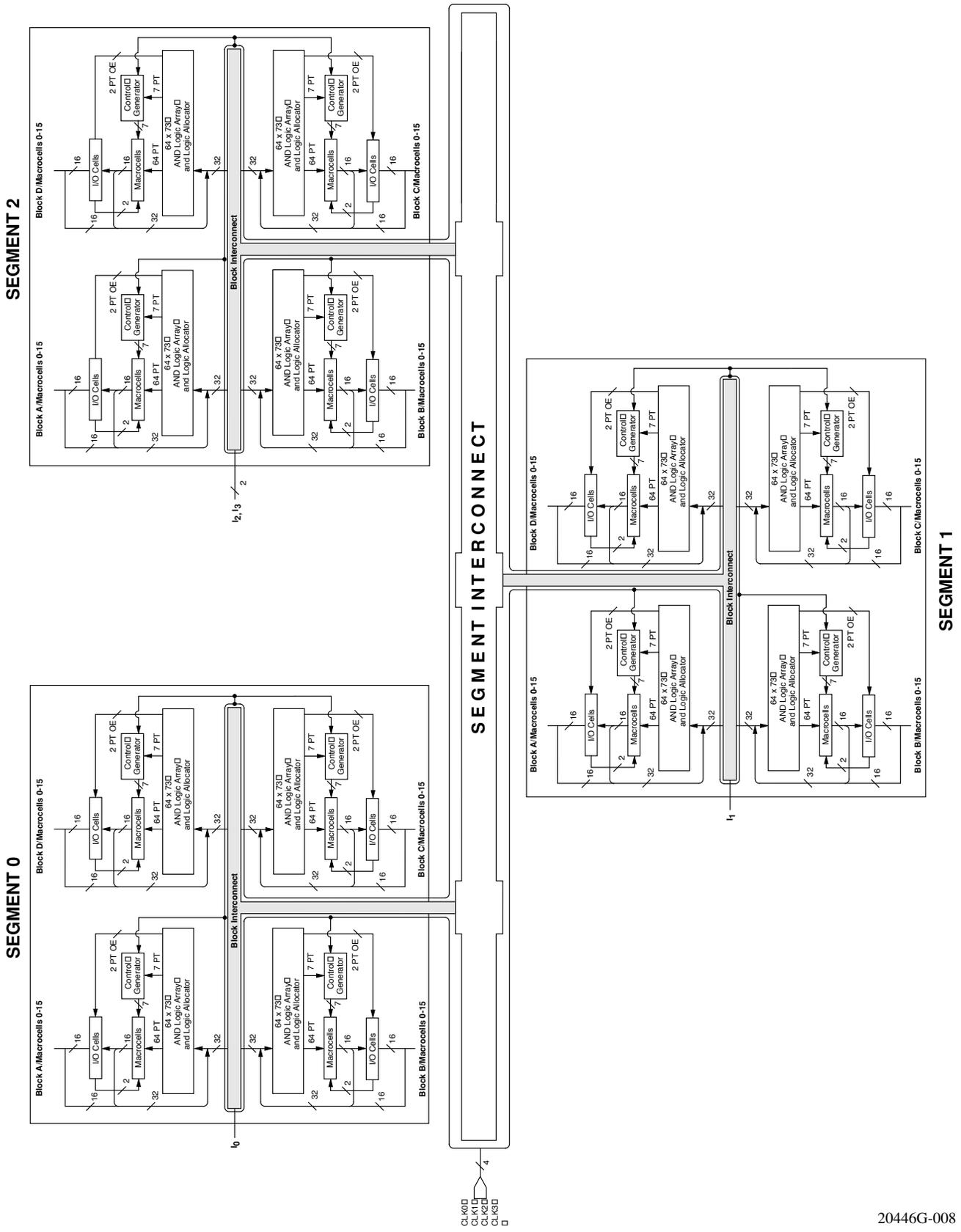


SEGMENT 1

20446G-007

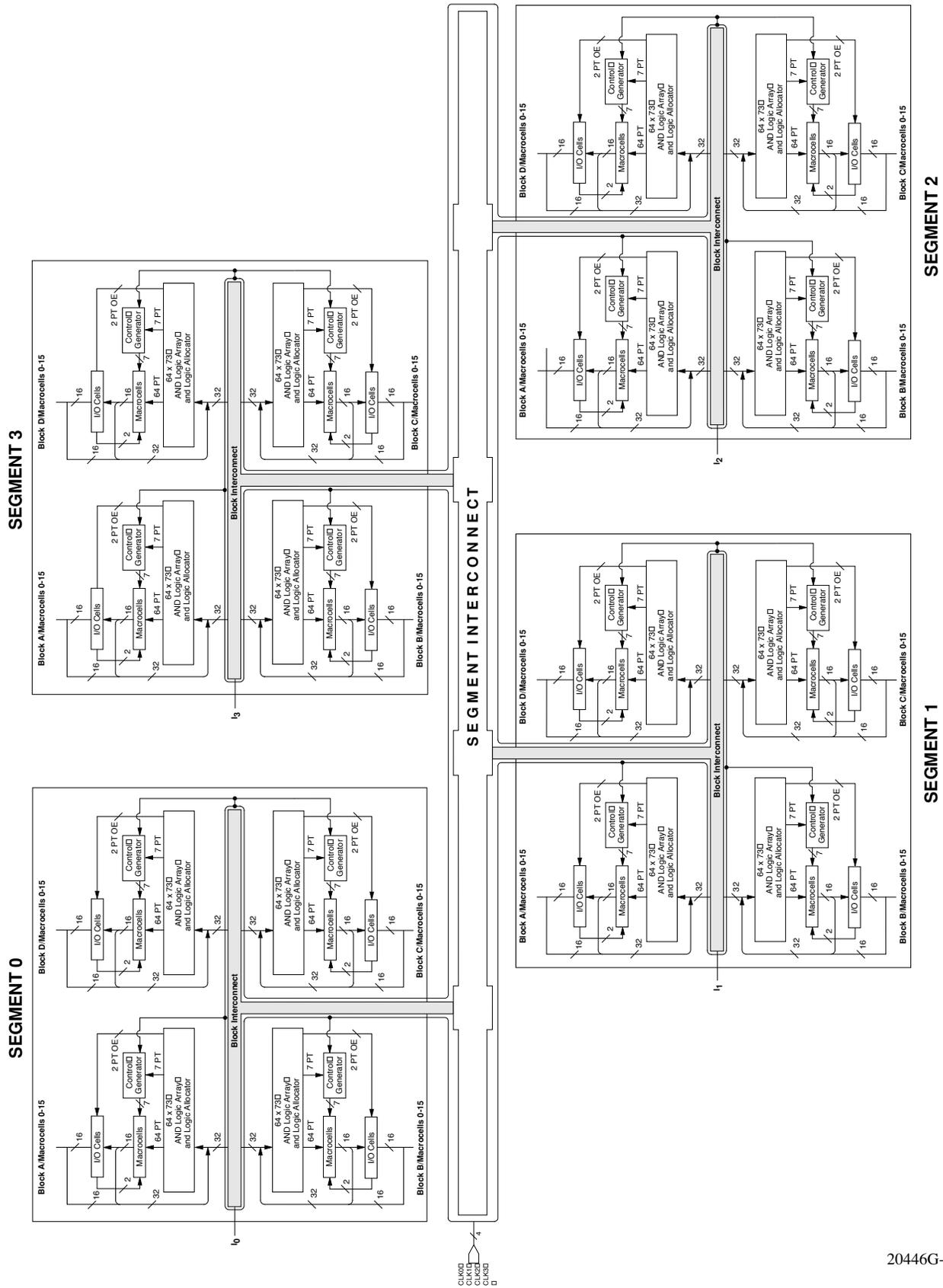
Select devices have been discontinued. See Ordering Information section for product status.

BLOCK DIAGRAM — M5-192/XXX



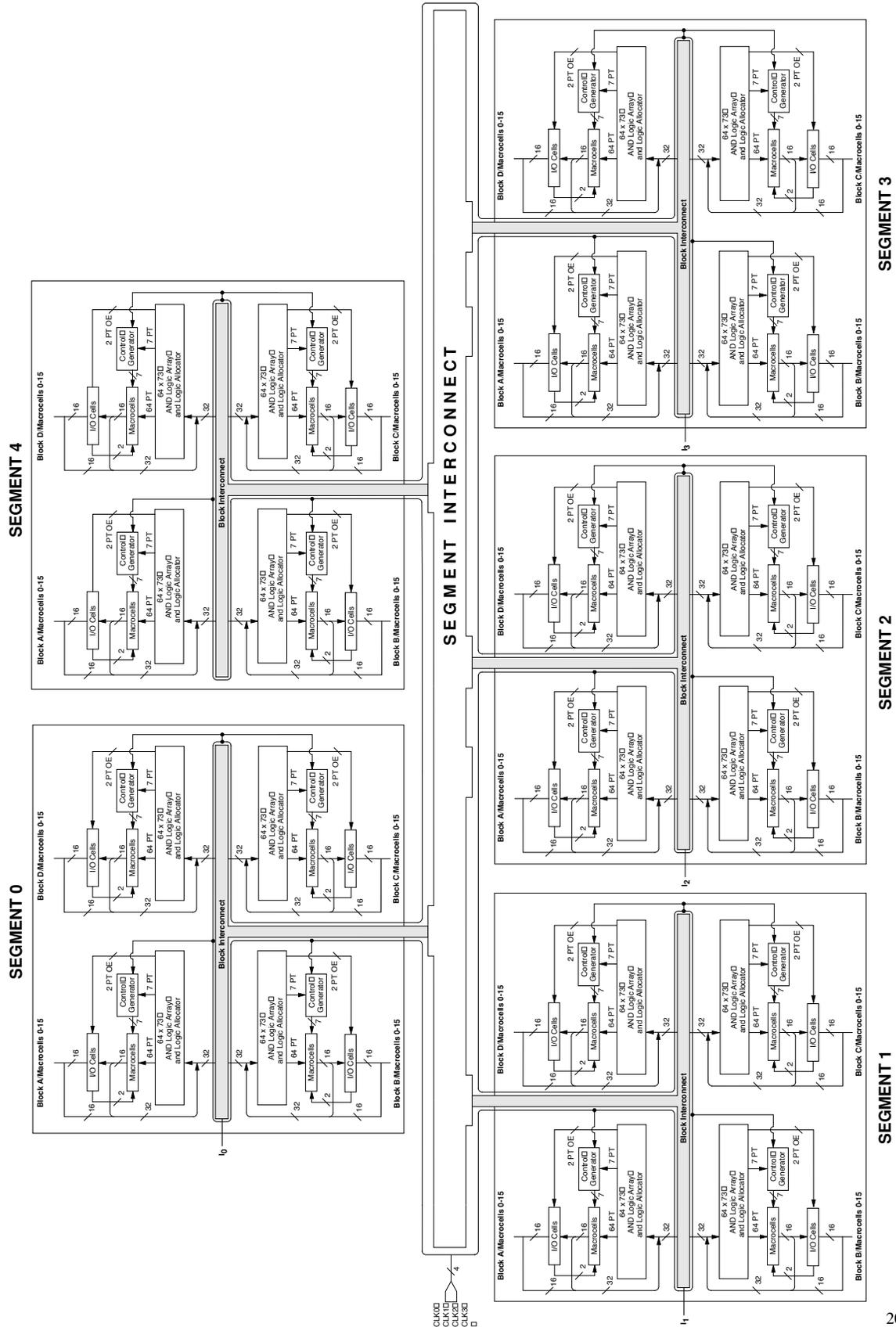
Select devices have been discontinued.
See Ordering Information section for product status.

BLOCK DIAGRAM — M5(LV)-256/XXX



Select devices have been discontinued.
 See Ordering Information section for product status.

BLOCK DIAGRAM — M5(LV)-320/XXX



Select devices have been discontinued.
See Ordering Information section for product status.

ABSOLUTE MAXIMUM RATINGS

M5

Storage Temperature	-65°C to +150°C
Device Junction Temperature (Note 1)	+130°C or +150°C
Supply Voltage with Respect to Ground	-0.5 V to +7.0 V
DC Input Voltage	-0.5 V to 5.5 V
Static Discharge Voltage	2000 V
Latchup Current (-40°C to +85°C)	200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)	Operating in Free Air	0°C to +70°C
Supply Voltage (V_{CC})	with Respect to Ground	+4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)	Operating in Free Air	-40°C to +85°C
Supply Voltage (V_{CC})	with Respect to Ground	+4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

Select devices have been discontinued. See Ordering Information section for product status.

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Description	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage (For M5-128/1, M5-192/1, M5-256/1, M5-320, M5-384, M5-512 Devices)	$I_{OH} = -3.2 \text{ mA}, V_{CC} = \text{Min}, V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
		$I_{OH} = -100 \mu\text{A}, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$		3.3	3.6	V
	Output HIGH Voltage (For M5-128, M5-192, M5-256 Devices)	$I_{OH} = -3.2 \text{ mA}, V_{CC} = \text{Min}, V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
		$I_{OH} = -2.5 \text{ mA}, V_{CC} = 5.25 \text{ V}, V_{IN} = V_{IH} \text{ or } V_{IL}$			3.6	V
V_{OL}	Output LOW Voltage (Note 2)	$I_{OL} = +16 \text{ mA}, V_{CC} = \text{Min}, V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 3)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 3)			0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25, V_{CC} = \text{Max}$ (Note 4)			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0, V_{CC} = \text{Max}$ (Note 4)			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$ (Note 4)			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$ (Note 4)			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5 V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$ (Note 5)	-30		-180	mA

Note:

- 150° for M5-128, M5-192 and M5-256 devices. 130° for M5-128/1, M5-192/1, M5-256/1, M5-320, M5-384 and M5-512 devices.
- Total I_{OL} between ground pins should not exceed 64 mA.
- These are absolute values with respect to device ground, and all overshoots due to system and/or tester noise are included.
- I/O pin leakage is the worst case of I_{IL} and I_{OZL} or I_{IH} and I_{OZH} .
- Not more than one output should be shorted at a time. Duration of the short-circuit should not exceed one second.

CAPACITANCE¹

Parameter Symbol	Parameter Description	Test conditions		Typ	Unit
C_{IN}	I/CLK pin	$V_{IN} = 2.0\text{ V}$	3.3 V or 5 V, 25° C, 1 MHz	12	pF
C_{VO}	I/O pin	$V_{OUT} = 2.0\text{ V}$	3.3 V or 5 V, 25° C, 1 MHz	10	pF

1. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where these parameters may be affected.

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power/Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power. For a more detailed discussion about MACH 5 power consumption, refer to the application note entitled *MACH 5 Power* in the Application Notes section on the Lattice Data Book CD-ROM or Lattice web site.

I_{CC} CURVES AT HIGH /LOW POWER MODES

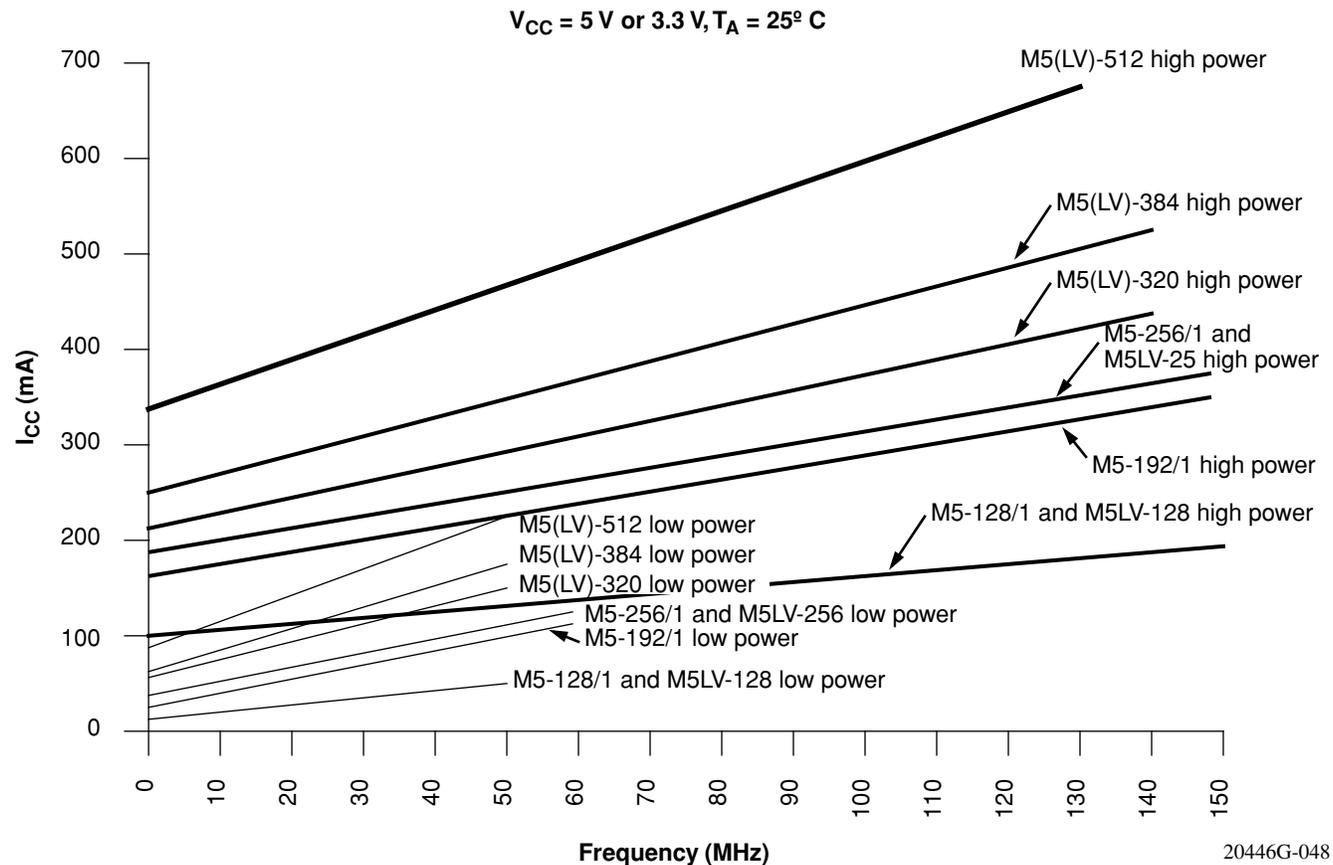


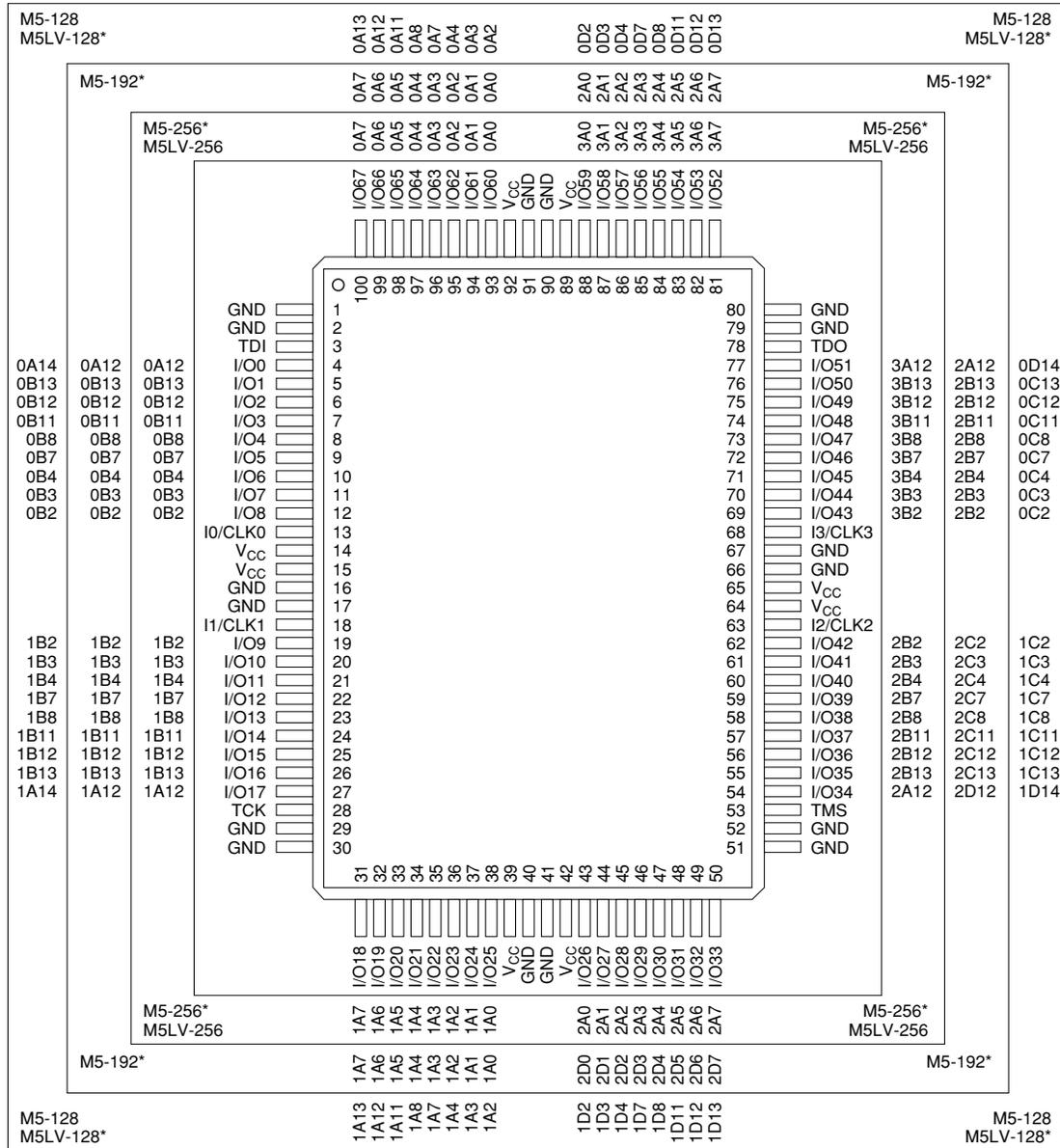
Figure 8. I_{CC} Curves at High/Low Power Modes

Select devices have been discontinued. See Ordering Information section for product status.

100-PIN PQFP CONNECTION DIAGRAM

Top View

100-Pin PQFP (68 I/O)



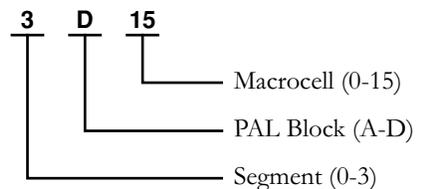
*Package obsolete, contact factory.

20446G-016

Select devices have been discontinued. See Ordering Information section for product status.

Pin Designations

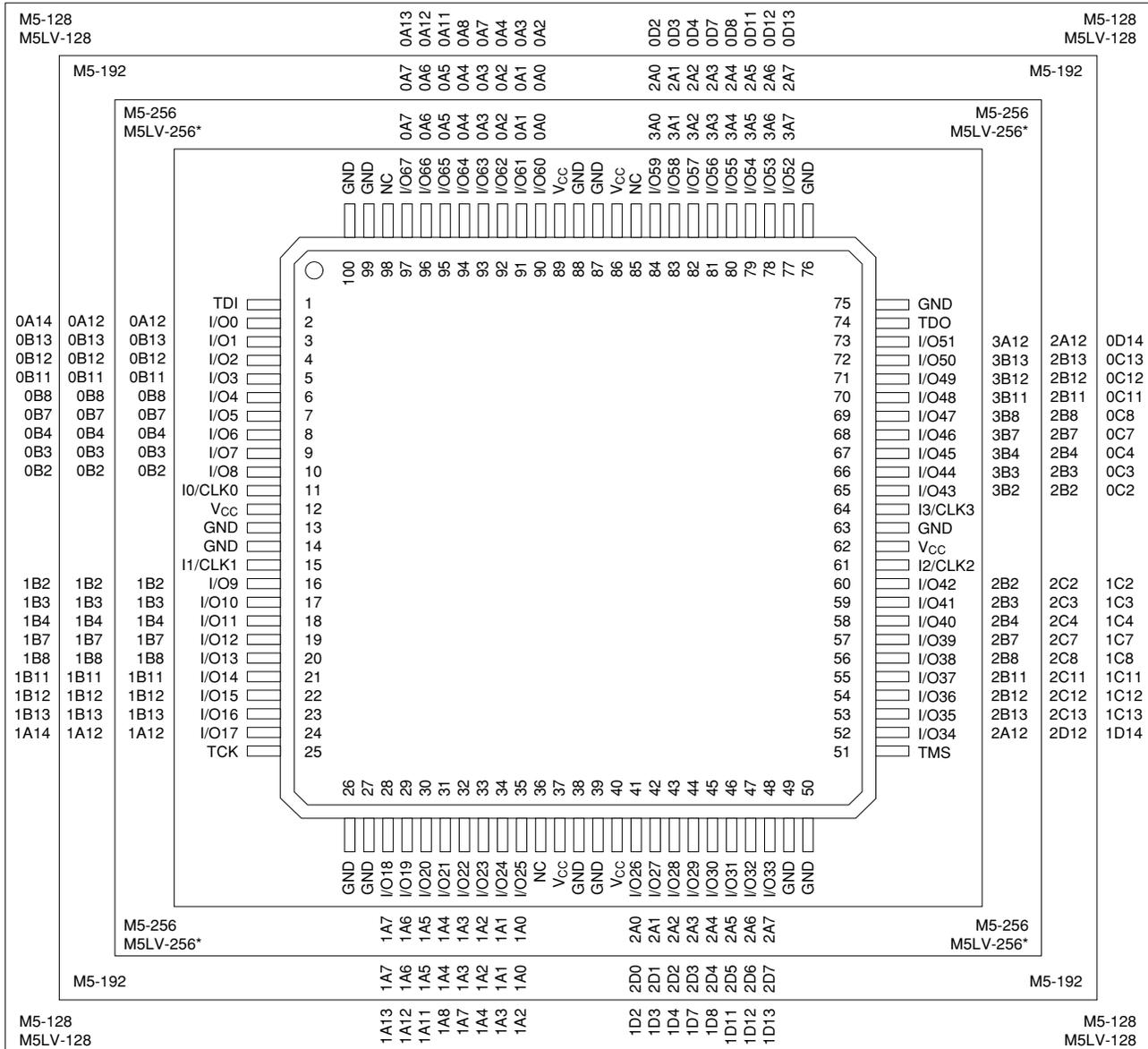
- | | |
|--------------------|----------------------------------|
| CLK = Clock | V _{CC} = Supply Voltage |
| GND = Ground | TDI = Test Data In |
| I = Input | TCK = Test Clock |
| I/O = Input/Output | TMS = Test Mode Select |
| NC = No Connect | TDO = Test Data Out |



100-PIN TQFP CONNECTION DIAGRAM – 68 I/O

Top View

100-Pin TQFP (68 I/O)



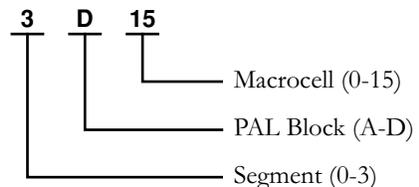
*Package obsolete, contact factory.

Select devices have been discontinued. See Ordering Information section for product status.

20446G-017

Pin Designations

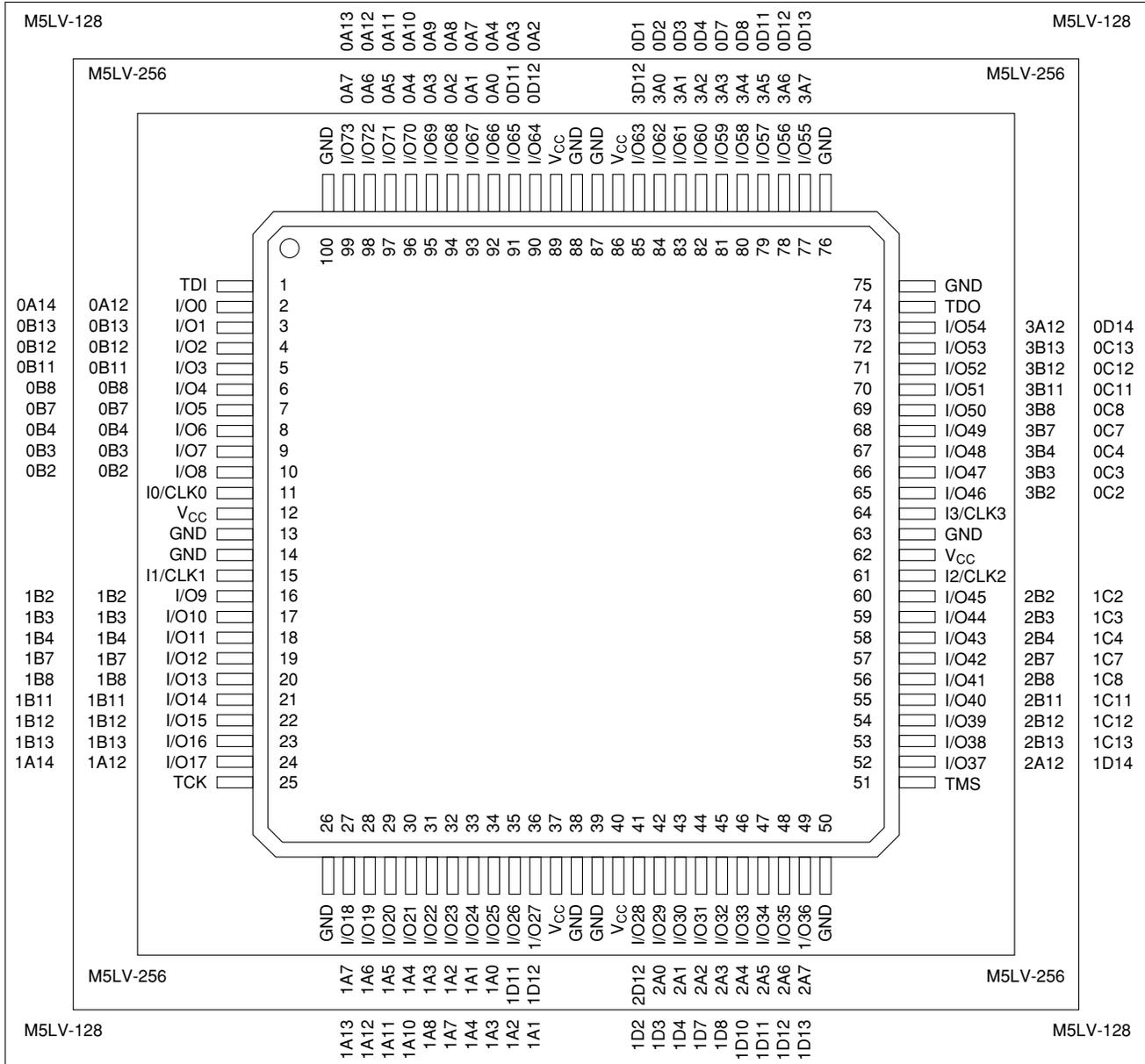
- | | |
|--------------------|----------------------------------|
| CLK = Clock | V _{CC} = Supply Voltage |
| GND = Ground | TDI = Test Data In |
| I = Input | TCK = Test Clock |
| I/O = Input/Output | TMS = Test Mode Select |
| NC = No Connect | TDO = Test Data Out |



100-PIN TQFP CONNECTION DIAGRAM – 74 I/O

Top View

100-Pin TQFP (74 I/O)

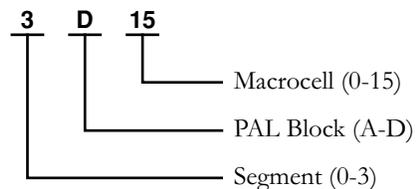


Select devices have been discontinued. See Ordering Information section for product status.

20446G-018

Pin Designations

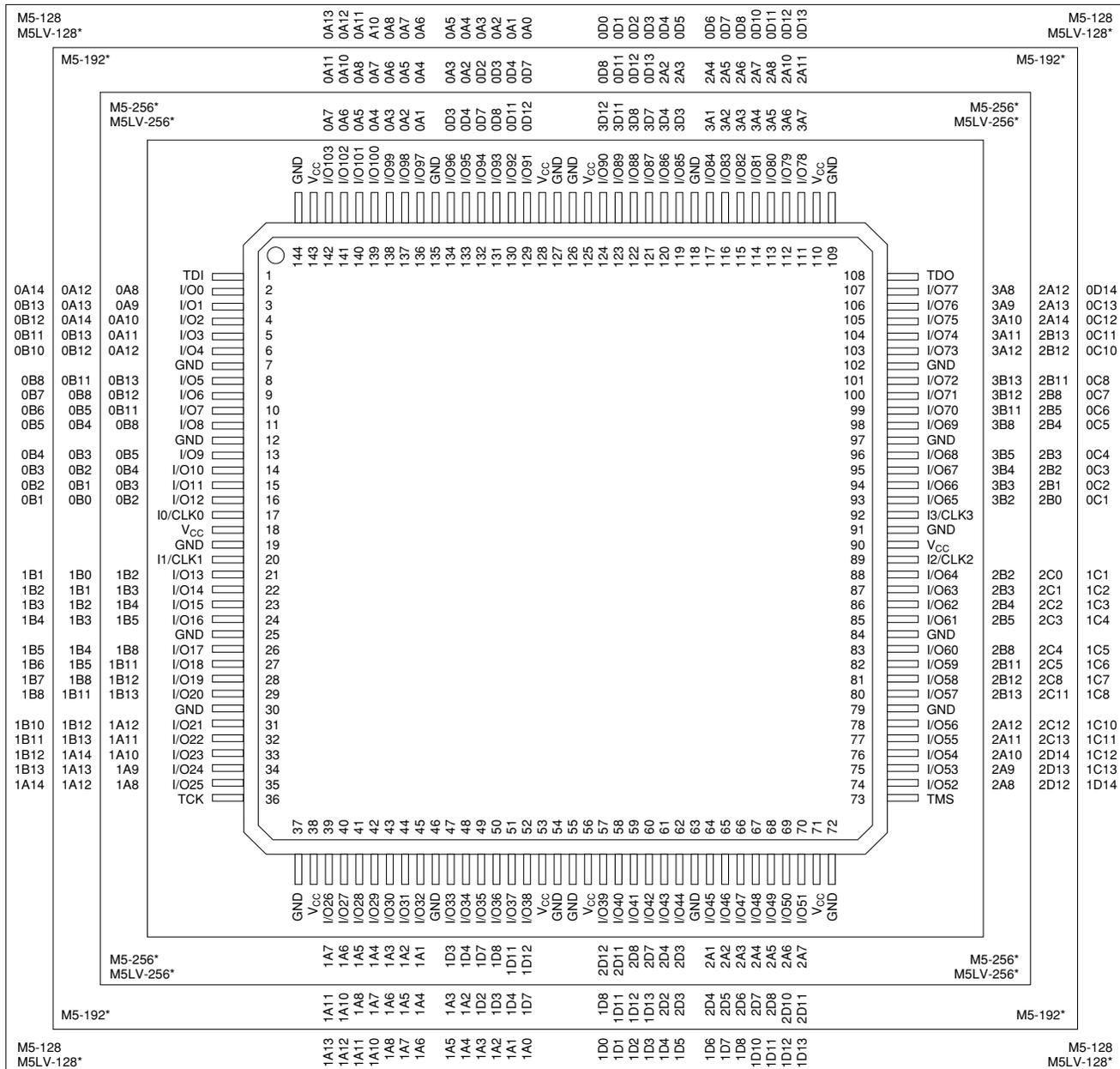
- | | |
|--------------------|----------------------------------|
| CLK = Clock | V _{CC} = Supply Voltage |
| GND = Ground | TDI = Test Data In |
| I = Input | TCK = Test Clock |
| I/O = Input/Output | TMS = Test Mode Select |
| NC = No Connect | TDO = Test Data Out |



144-PIN PQFP CONNECTION DIAGRAM

Top View

144-Pin PQFP



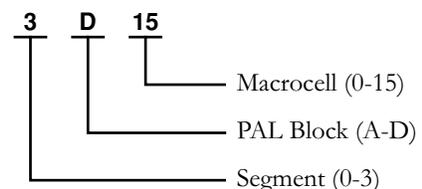
Select devices have been discontinued. See Ordering Information section for product status.

*Package obsolete, contact factory.

20446G-019

Pin Designations

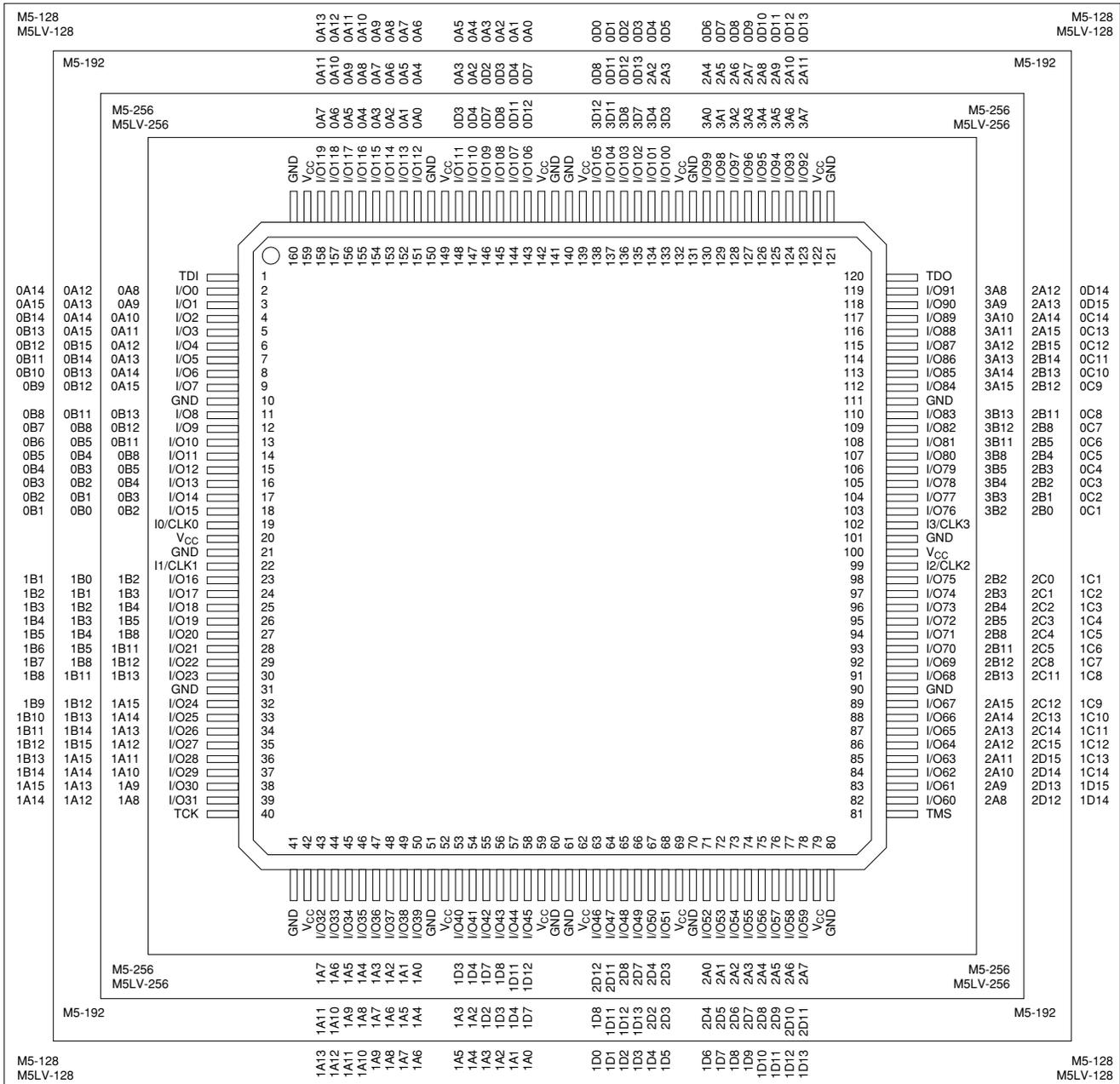
- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- NC = No Connect
- V_{CC} = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
- TMS = Test Mode Select
- TDO = Test Data Out



160-PIN PQFP CONNECTION DIAGRAM

Top View

160-Pin PQFP (128, 192, 256 Macrocells)

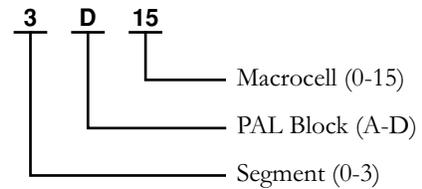


Select devices have been discontinued. See Ordering Information section for product status.

20446G-021

Pin Designations

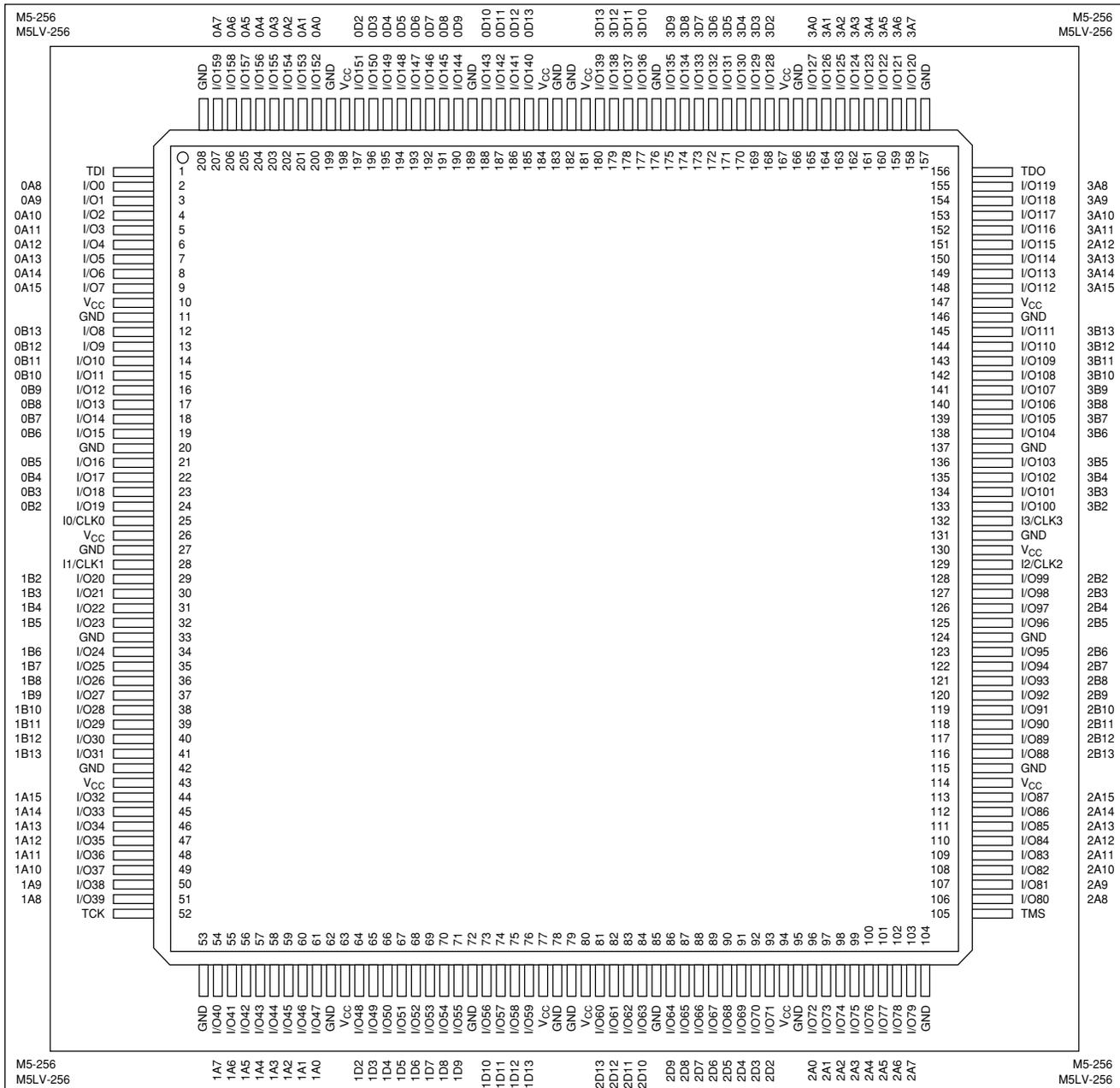
- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- NC = No Connect
- V_{CC} = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
- TMS = Test Mode Select
- TDO = Test Data Out



208-PIN PQFP CONNECTION DIAGRAM

Top View

208-Pin PQFP (256 Macrocells)

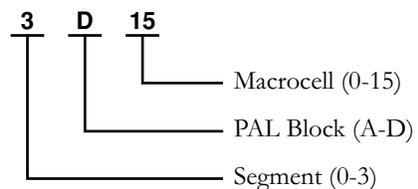


Select devices have been discontinued. See Ordering Information section for product status.

20446G-023

Pin Designations

- | | |
|--------------------|----------------------------------|
| CLK = Clock | V _{CC} = Supply Voltage |
| GND = Ground | TDI = Test Data In |
| I = Input | TCK = Test Clock |
| I/O = Input/Output | TMS = Test Mode Select |
| NC = No Connect | TDO = Test Data Out |



256-BALL BGA CONNECTION DIAGRAM — M5-320

Bottom View (I/O Pin-outs)

256-Ball BGA

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y
20	GND	I/O12	I/O13	I/O14	I/O15	GND	I/O3	GND	I/O4	GND	I/O5	I/O6	GND	I/O7	GND	I/O8	I/O9	I/O10	GND	GND
19	I/O11	I/O28	V _{CC}	I/O29	I/O30	I/O16	I/O17	I/O18	I/O19	I/O/CLK0	I1/CLK1	I/O20	I/O21	I/O22	I/O23	I/O24	I/O25	I/O26	I/O27	GND
18	GND	I/O44	I/O46	V _{CC}	TDI	TDI	V _{CC}	I/O48	I/O49	I/O50	I/O51	I/O52	I/O53	V _{CC}	I/O54	TCK	V _{CC}	V _{CC}	I/O43	GND
17	I/O45	I/O47	I/O48	I/O49	I/O50	I/O51	I/O52	I/O53	I/O54	I/O55	I/O56	I/O57	I/O58	I/O59	I/O60	I/O61	I/O62	I/O63	I/O64	I/O65
16	I/O58	I/O59	I/O60	V _{CC}	V _{CC}	I/O67	I/O68	I/O69	I/O70	I/O71	I/O72	I/O73	I/O74	I/O75	I/O76	I/O77	I/O78	I/O79	I/O80	I/O81
15	GND	I/O64	I/O65	I/O66	I/O67	I/O68	I/O69	I/O70	I/O71	I/O72	I/O73	I/O74	I/O75	I/O76	I/O77	I/O78	I/O79	I/O80	I/O81	I/O82
14	I/O70	I/O71	I/O72	V _{CC}	V _{CC}	I/O87	I/O88	I/O89	I/O90	I/O91	I/O92	I/O93	I/O94	I/O95	I/O96	I/O97	I/O98	I/O99	I/O100	I/O101
13	I/O76	I/O77	I/O78	I/O79	I/O80	I/O81	I/O82	I/O83	I/O84	I/O85	I/O86	I/O87	I/O88	I/O89	I/O90	I/O91	I/O92	I/O93	I/O94	I/O95
12	GND	I/O84	I/O85	I/O86	I/O87	I/O88	I/O89	I/O90	I/O91	I/O92	I/O93	I/O94	I/O95	I/O96	I/O97	I/O98	I/O99	I/O100	I/O101	I/O102
11	GND	I/O90	I/O91	I/O92	I/O93	I/O94	I/O95	I/O96	I/O97	I/O98	I/O99	I/O100	I/O101	I/O102	I/O103	I/O104	I/O105	I/O106	I/O107	I/O108
10	GND	I/O96	I/O97	I/O98	I/O99	I/O100	I/O101	I/O102	I/O103	I/O104	I/O105	I/O106	I/O107	I/O108	I/O109	I/O110	I/O111	I/O112	I/O113	I/O114
9	GND	I/O102	I/O103	I/O104	I/O105	I/O106	I/O107	I/O108	I/O109	I/O110	I/O111	I/O112	I/O113	I/O114	I/O115	I/O116	I/O117	I/O118	I/O119	I/O120
8	I/O108	I/O109	I/O110	I/O111	I/O112	I/O113	I/O114	I/O115	I/O116	I/O117	I/O118	I/O119	I/O120	I/O121	I/O122	I/O123	I/O124	I/O125	I/O126	I/O127
7	GND	I/O116	I/O117	I/O118	I/O119	I/O120	I/O121	I/O122	I/O123	I/O124	I/O125	I/O126	I/O127	I/O128	I/O129	I/O130	I/O131	I/O132	I/O133	I/O134
6	GND	I/O128	I/O129	I/O130	V _{CC}	V _{CC}	I/O134	I/O135	I/O136	I/O137	I/O138	I/O139	I/O140	I/O141	I/O142	I/O143	I/O144	I/O145	I/O146	I/O147
5	I/O128	I/O129	I/O130	V _{CC}	V _{CC}	I/O134	I/O135	I/O136	I/O137	I/O138	I/O139	I/O140	I/O141	I/O142	I/O143	I/O144	I/O145	I/O146	I/O147	I/O148
4	I/O134	I/O135	I/O136	V _{CC}	V _{CC}	I/O148	I/O149	I/O150	I/O151	I/O152	I/O153	I/O154	I/O155	I/O156	I/O157	I/O158	I/O159	I/O160	I/O161	I/O162
3	GND	I/O148	V _{CC}	I/O149	I/O150	I/O151	I/O152	I/O153	I/O154	I/O155	I/O156	I/O157	I/O158	I/O159	I/O160	I/O161	I/O162	I/O163	I/O164	I/O165
2	GND	I/O164	I/O165	I/O166	I/O167	I/O168	I/O169	I/O170	I/O171	I/O172	I/O173	I/O174	I/O175	I/O176	I/O177	I/O178	I/O179	I/O180	I/O181	I/O182
1	GND	GND	I/O181	I/O182	I/O183	GND	I/O184	GND	I/O185	I/O186	GND	I/O187	GND	I/O188	GND	I/O189	I/O190	I/O191	GND	GND

Pin Designations

- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- NC = No Connect
- V_{CC} = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
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